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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Application Number : 10/731,482 Confirmation No. 5381
Applicant : Joon Hyeon LEE
Filed : December 10, 2003
Tech Cntr/AU : 2812
Examiner : Lynne Ann Gurley
Entitled : METHOD OF FORMING METAL LINE LAYER IN SEMICONDUCTOR DEVICE

Attorney Reference : 123034-05004728
Customer Number : 43569

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

AMENDMENT/RESPONSE TRANSMITTAL

Transmitted herewith is an amendment/response for this application.

EXTENSION OF TIME

A petition for extension of time under 37 C.F.R. 1.136 is not believed necessary.

CLAIM FEES

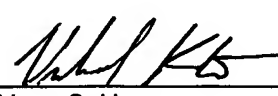
The claim fees have been calculated as follows:

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total	12	- 20	= 0	x \$ 50.00	= \$ 0.00
Independent	2	- 3	= 0	x \$ 200.00	= \$ 0.00
FIRST PRESENTATION OF MULTIPLE DEP. CLAIM+ \$ 360.00					= \$ 0.00
TOTAL ADDITIONAL CLAIM FEE DUE					\$ 0.00

FEE PAYMENT

Authorization is given herein to charge the any deficiencies in the fees not specifically authorized herein, or to further credit any overpayments, to Deposit Account No. 503-121 in order to maintain the pendency of this application.

Intellectual Property Department
Mayer Brown Rowe & Maw LLP
1909 K Street, N.W.
Washington, D.C. 20006-1101

for  Reg No. 51,813
Yoon S. Ham
Registration No. 45,307
(202) 263-3280

Date: March 21, 2006



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RESPONSE UNDER 37 C.F.R. § 1.116

Sir:

In response to the Office Action dated July 13, 2005 for the above-identified application, amendments and/or remarks submitted herewith include:

- Amendments to the Specification;
- A complete claim listing; and
- Remarks and arguments.